


Testing Digital Systems I

Lecture 1: Introduction

Instructor: M. Tahoori

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Today's Lecture

- Logistics
- Course Outline
- Introduction

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Logistics

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- Lecture:
 - When: Wednesdays 9:45-11:15
 - Where: Room -120, Building 50.34



Logistics (cont)

- Requirements
 - Logic Design
 - Computer Architecture
- Background on (preferred but not required)
 - Algorithms and Programming
 - Hardware description languages (VHDL or Verilog)



Reference Books


- Textbook
 - **Essentials of Electronic Testing for Digital, Memory and Mixed-Signal VLSI Circuits** by M. L. Bushnell and V.D. Agrawal, *Kluwer Academic Press*, Boston 2000
- Recommended
 - **System On Chip Test Architectures: Nanometer Design for Testability** by L.T. Wang, C.E. Stroud, N. A. Toubia, Elsevier, Morgan Kaufmann Publishers, 2009.
 - **Digital System Testing and Testable Design** by M. Abramovici, M. A. Breuer, and A.D. Friedman, *IEEE Press*, New York, 1990, 652 pages



Course Outline

- Basics
- Test generation methods
- Design for Testability (DFT)


- I try to be flexible. The order and contents may be changed as we proceed.



Outline: Basics

- Introduction
- Failures and errors
- Fault models
- Functional vs Structural testing


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Outline: Test Generation

- Test generation techniques and algorithms for combinational logic
- Essentials of test generation methods for sequential circuits
- Logic and fault simulation


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Outline: Design For Testability (DFT)

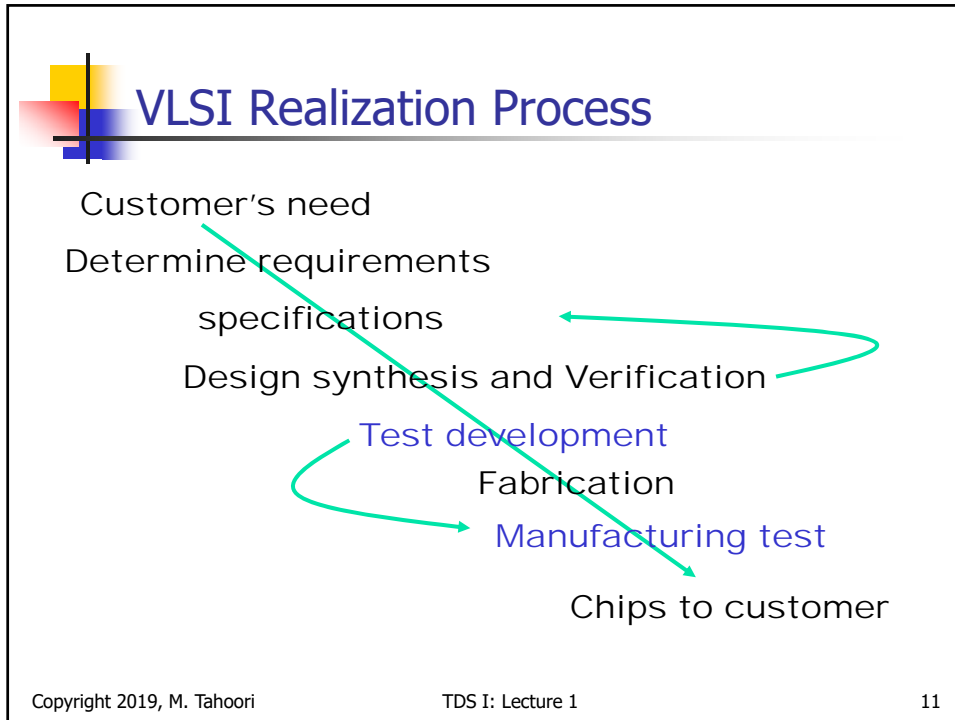
- Ad hoc DFT techniques
- Internal scan design
- Boundary scan

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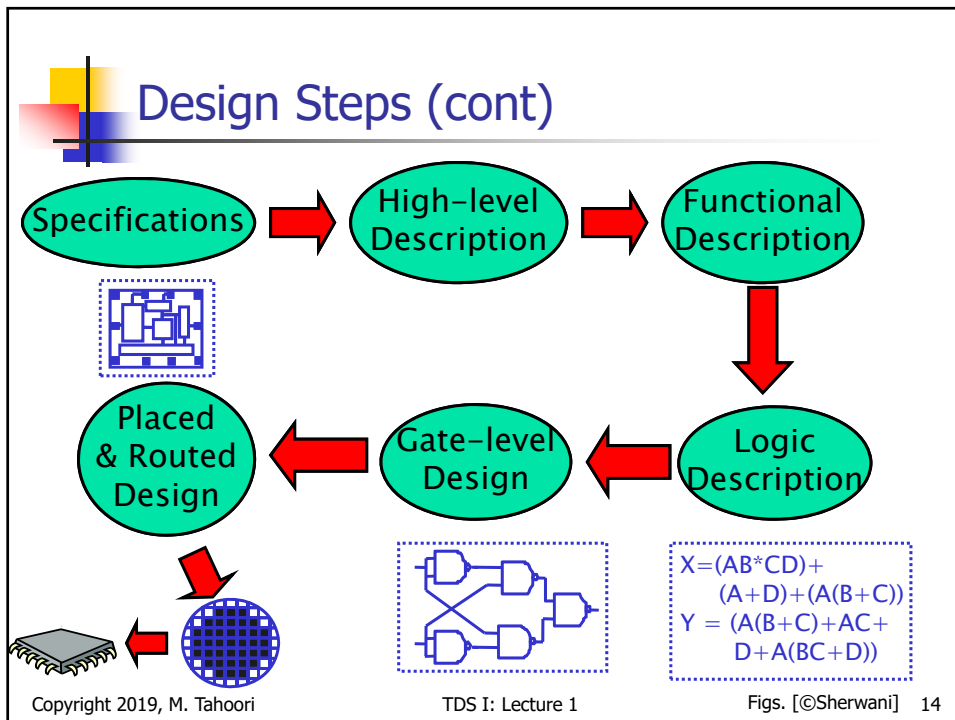
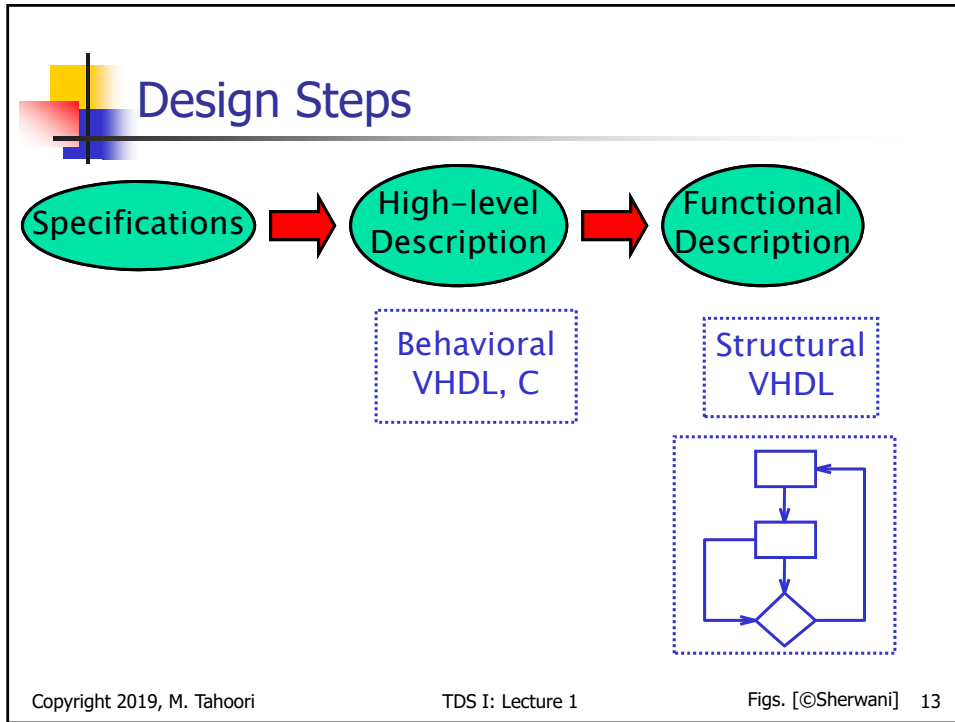


Introduction

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-
- Definitions**
- Design synthesis:
 - Given an Input-Output function, develop a procedure to manufacture a device using known materials and processes
 - Verification:
 - Predictive analysis to ensure that the synthesized design, when manufactured, will perform the given Input-Output function
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Testing

- The process of determining whether a piece of device
 - Is functioning correctly, or
 - Is defective (broken or faulty)
- Equipment can be defective because it doesn't function
 - as designed, or
 - as specified



Testing (cont)

- The need for test depends on
 - Process yield, Y ,
 - the proportion of finished units that are not defective
 - Depends on maturity of the manufacturing process, size of the integrated circuit chips and the characteristics of the implemented design, etc.
 - Acceptable quality level (AQL)
 - the planned minimum fraction of defective shipped units
 - Defective Parts per Million (DPM)
 - Depends on the volume of the product, criticality of the applications and the cost of the parts

Yield and Quality Level

- Y and AQL are rarely exactly known
 - Statistically estimated
 - Not feasible to thoroughly test all parts
- Process yield is typically less than AQL
 - defective units must be identified and removed so as to increase the percentage of good units shipped to the customer.

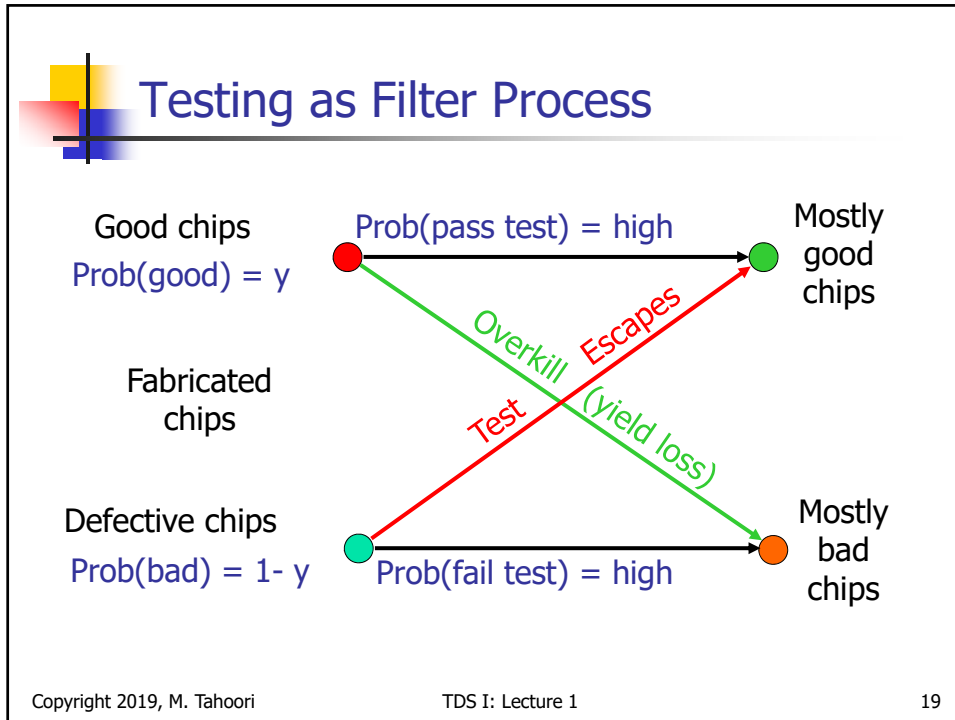
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Testing Process


```
graph TD; A[Components, Raw Materials] --> B[Manufacturing Process]; B -- "Yield  
Fraction of good parts  
20%-90%" --> C[Testing]; C -- "Shipped Parts  
Quality: DPM  
Defective Parts per Million  
50-500 DPM" --> D[Shipped Parts];
```

The diagram illustrates the testing process flow. It starts with 'Components, Raw Materials' which feed into a 'Manufacturing Process' box. An arrow labeled 'Yield' points from the 'Manufacturing Process' to a 'Testing' box, with the text 'Fraction of good parts' and '20%-90%' below it. From the 'Testing' box, an arrow labeled 'Shipped Parts' points to the right, with the text 'Quality: DPM Defective Parts per Million' and '50-500 DPM' below it.

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- ## A Part Fails to Operate
- Design Does Not Correspond to Specification
 - Logic Design Incorrect
 - Physical Design Incorrect
 - Physical Part Does Not Correspond to Design
 - Manufacturing Defect Present
 - Wear Out Defect Present
 - External or Environmental Disturbance
 - Transient Disturbance
 - Power or Temperature Specification Violated
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Logic Design Verification

- Specification
 - Behavioral or Register Transfer
 - Table of Combinations – Boolean Function
 - Sequential Circuit or State Machine Flow Table
 - Simulation Vectors and Responses
 - Informal Word Description of Functionality
- Verification Technique
 - Synthesis
 - Matching of Two Design Paths
 - Simulation — Emulation
 - Formal Verification

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Verification vs. Test

| | |
|---|---|
| <ul style="list-style-type: none">■ Verifies correctness of design.■ Performed by simulation, hardware emulation, or formal methods.■ Performed once prior to manufacturing.■ Responsible for quality of design. | <ul style="list-style-type: none">■ Verifies correctness of manufactured hardware.■ Two-part process:<ul style="list-style-type: none">■ 1. Test generation: software process executed once during design■ 2. Test application: electrical tests applied to hardware■ Test application performed on every manufactured device.■ Responsible for quality of devices. |
|---|---|

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Problems of Ideal Tests

- Definition
 - Ideal tests detect all defects produced in the manufacturing process.
 - Ideal tests pass all functionally good devices.
- Problems
 - Very large numbers and varieties of possible defects need to be tested.
 - Difficult to generate tests for some real defects.
 - Unacceptable test costs
 - Test generation effort, test application time



Real Tests

- Based on analyzable fault models, which may not map on real defects.
- Incomplete coverage of modeled faults due to high complexity.
- Some good chips are rejected
 - The fraction (or percentage) of such chips is called the *yield loss*.
- Some bad chips pass tests
 - The fraction (or percentage) of bad chips among all passing chips is called the *defect level*.



VLSI Technology an Trends

- These trends impact cost and difficulty of testing

| Year | 1999 | 2002 | 2005 | 2008 | 2011 | 2014 |
|------------------------------|-------|------|------|------|-------|-------|
| Feature size (nm) | 180 | 130 | 100 | 70 | 50 | 35 |
| Logic trans/cm ² | 6.2M | 18M | 39M | 84M | 180M | 390M |
| Cost/trans (mc) | 1.735 | .580 | .255 | .110 | .049 | .022 |
| #pads/chip | 1867 | 2553 | 3492 | 4776 | 6532 | 8935 |
| Clock (MHz) | 1250 | 2100 | 3500 | 6000 | 10000 | 16900 |
| Chip size (mm ²) | 340 | 430 | 520 | 620 | 750 | 900 |
| Wiring levels | 6-7 | 7 | 7-8 | 8-9 | 9 | 10 |
| Power supply (V) | 1.8 | 1.5 | 1.2 | 0.9 | 0.6 | 0.5 |
| High-perf pow (W) | 90 | 130 | 160 | 170 | 175 | 183 |



Costs of Testing

- *Design for testability* (DFT)
 - Chip area overhead
 - Yield reduction
 - Performance overhead
- Software processes of test
 - Test generation
 - Fault simulation
 - Test programming and debugging
- Manufacturing test
 - *Automatic test equipment* (ATE) capital cost
 - Test center operational cost

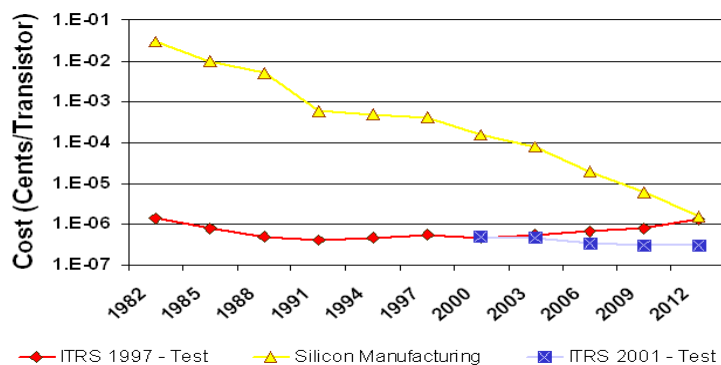


Example: Cost of Testing

- 0.5-1.0GHz, analog instruments, 1,024 digital pins:
ATE purchase price
 - = $\$1.2\text{M} + 1,024 \times \$3,000 = \$4.272\text{M}$
- Running cost (five-year linear depreciation)
 - = Depreciation + Maintenance + Operation
 - = $\$0.854\text{M} + \$0.085\text{M} + \$0.5\text{M}$
 - = $\$1.439\text{M}/\text{year}$
- Test cost (24 hour ATE operation)
 - = $\$1.439\text{M}/(365 \times 24 \times 3,600)$
 - = 4.5 cents/second
- Digital ASIC test time: 6 seconds or 27 cents



Cost of Manufacturing Test



Source: International Technology Roadmap for Semiconductor Industry (ITRS)



Roles of Testing

- Detection:
 - Determination whether or not the *device under test* (DUT) has some fault.
- Diagnosis:
 - Identification of a specific fault that is present on DUT.
- Device characterization:
 - Determination and correction of errors in design and/or test procedure.
- *Failure mode analysis* (FMA):
 - Determination of manufacturing process errors that may have caused defects on the DUT.



Who Needs to Take This Class?

- Testing (Test & DFT Engineer)
 - Needs to focus on all topics,
 - More emphasize on test flow and tools
- Design automation (CAD Engineer)
 - Focus on test generation and DFT algorithms
 - Test automation
- Circuit design and computer architecture (Designer)
 - Focus on DFT techniques
 - Testable designs
 - Interaction of test flow and design flow
 - How DFT affect the original design

CDNC Teaching Modules

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Practical Introduction to HW Security

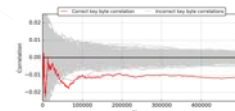
M. Tahoori, D. Gnad,
J. Krautter


Practical Introduction to Hardware Security



- Lecture and lab in SS2019, 4 SWS/6 ECTS
- Thursday (starting 25. April), 14:00-17:00 in *Technologiefabrik* Haid-und-Neu-Str. 7 (Building 07.21) Rooms A.1.8 - A.1.10 (first floor)
- Topics:
 - Security primitives and their implementation
 - Side-channel attacks
 - Fault attacks
 - Actual experiments on a Lattice iCE40HX8K FPGA device!
- **Sign-up** online and join tomorrow! (Lecture No. 2400009)

```
Practical introduction:
Hexview signature: 82 a2 09 03 4a 0f 05 0a 4f 43 21 0a c9 09 04 02
Binary signature: 80 c0 00 00 00 00 00 00 00 00 00 00 00 00 00 00
SHA256 signature: 4a 09 05 42 3a 12 1a 02 0a 09 0a 0a 0a 0a 0a 0a 0a
Practical introduction: 0a 00 13 02 0a 12 1a 02 0a 09 0a 0a 0a 0a 0a 0a 0a
Hexview fault injection:
Hexview signature: 44 01 0a c0 3a 0a 0a 11 09 0f 0a 02 0a 0a 0a 0a
Binary signature: 10 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00
```








Labs

- **FPGA Programming**
 - Introduction to FPGAs
 - Circuit development for FPGAs
 - Hands-on experiments with FPGAs

- **Intel Galileo Design Lab**
 - Introduction to Intel Galileo
 - Circuit development
 - Hands-on experiments

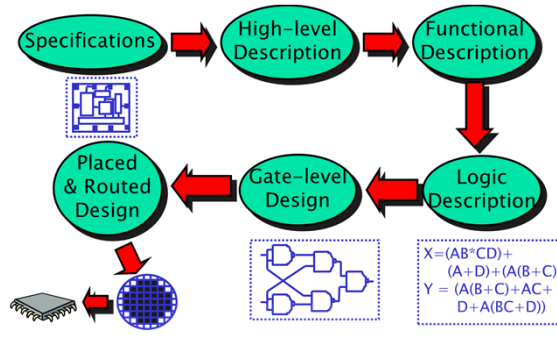



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Labs

- **Digital Design and Test Flow**
 - Introduction to algorithms and tools for Electronic Design Automation
 - The entire design flow from specification to chips




The diagram illustrates the digital design and test flow. It starts with 'Specifications' (represented by a circuit board icon), which leads to 'High-level Description' (represented by a block diagram icon). This then leads to 'Functional Description' (represented by a logic symbol icon). From 'Functional Description', the flow goes down to 'Logic Description' (represented by a logic gate icon), which then leads to 'Gate-level Design' (represented by a logic gate icon). This leads to 'Placed & Routed Design' (represented by a chip icon), which finally leads to the physical chip (represented by a chip icon). A box next to the 'Logic Description' step contains the following Boolean expressions:

$$X = (AB \cdot CD) + (A + D) + (A(B + C))$$

$$Y = (A(B + C) + AC + D + A(BC + D))$$

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Seminars

- Non-Volatile Memory Technologies
 - Introduction to non-volatile memories
 - Can these be used to replace SRAM/DRAM?

- Near Threshold Computing
 - Ultra-low power computing for Internet of Things (IoT) platforms
 - Advantage: Huge power savings
 - Challenge: Performance degradation, reliability issues

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HiWi and Master Projects

- Hiwi positions
 - To help with various research projects in dependable computing
 - Required knowledge
 - Programming
 - Digital design and computer architecture (DT+RO)

- Master Projects
 - Various projects related to
 - Hardware security
 - Dependable computing
 - Emerging non-volatile memories

Contact us if interested & for more details: cdnc@ira.uka.de

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